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**AMENDMENTS TO THE CLAIMS:**

**Please cancel claims 12-25 without prejudice or disclaimer.**

1. (Currently amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that emits light with a predetermined wavelength;

a light-transmitting portion that includes a recess to house the semiconductor light emitting element, the light-transmitting portion being of a light-transmitting material and the recess being formed with a predetermined size provided by molding the light-transmitting material; and

a phosphor layer portion that is thinly formed along the surface of the recess, the phosphor layer portion including a phosphor to be excited by irradiating light emitted from the semiconductor light emitting element.

2. (Currently amended) The light emitting apparatus according to claim 1, wherein [[:]] the light-transmitting portion has a light convergence shape to converge light emitted from the light emitting element.

3. (Currently amended) The light emitting apparatus according to claim 1, wherein [[:]] the semiconductor light emitting element is a flip-chip type LED element that emits light from its light emission surface located on the opposite side of its mounting surface.

4. (Currently amended) The light emitting apparatus according to claim 1, wherein [[:]] the recess is located close to the semiconductor light emitting element along the profile of the semiconductor light emitting element.

5. (Currently amended) The light emitting apparatus according to claim 1, wherein [[:]] the semiconductor light emitting element is composed of a plurality of LED elements disposed in a predetermined arrangement.

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6. (Currently amended) The light emitting apparatus according to claim 1, wherein [[:]] the semiconductor light emitting element is composed of a plurality of LED elements with different emission wavelengths disposed in a predetermined arrangement.

7. (Currently amended) A method of making a light emitting apparatus, comprising the steps of:

preparing a light-transmitting portion that includes a recess to house a semiconductor light emitting element, the light-transmitting portion being of a light-transmitting material and the recess being formed with a predetermined size provided by molding the light-transmitting material, the recess being provided with a phosphor layer that is thinly formed along the surface of the recess;

forming an electrode of metal material;

mounting the semiconductor light emitting element on the electrode;

positioning the light-transmitting portion adjacent to the electrode; and

bonding the light-transmitting portion onto the electrode such that the phosphor layer of the recess surrounds an upper portion of the semiconductor light emitting element.

8. (Currently amended) The method according to claim 7, wherein [[:]] the phosphor layer is formed by spraying a phosphor material on the surface of the recess after forming the recess by molding.

9. (Currently amended) The method according to claim 7, wherein [[:]] the electrode is a lead electrode provided on the surface of a submount member of high thermal conductivity.

10. (Currently amended) The method according to claim 7, wherein [[:]] the electrode is a copper-foil electrode provided through an insulation layer on the surface of a base member of high thermal conductivity.

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11. (Currently amended) The method according to claim 7, wherein [[:]] the semiconductor light emitting element is flip-chip bonded onto the electrode.

12-25. (Canceled)

26. (New) The apparatus according to claim 1, further comprising:  
a sealant formed between said light emitting element and said phosphor layer portion, for sealing said light-emitting element,  
wherein said sealant comprises a transparent silicon resin.

27. (New) The apparatus according to claim 1, further comprising:  
a plurality of leads; and  
a submount formed on said plurality of leads, said light emitting element being formed on said submount.

28. (New) The apparatus according to claim 27, wherein said submount comprises a thermally conductive submount.

29. (New) The apparatus according to claim 27, wherein said light transmitting portion is formed on said plurality of leads, said recess being aligned with said light emitting element.

30. (New) The apparatus according to claim 27, further comprising:  
a wiring pattern formed on said submount, said light emitting element being mounted on said wiring pattern.

31. (New) The apparatus according to claim 30, wherein said light emitting element is flip-chip bonded through bumps onto the wiring pattern.

32. (New) The apparatus according to claim 30, wherein said submount comprises a

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viahole, said wiring pattern being electrically connected through said viahole to said lead.

33. (New) The apparatus according to claim 1, wherein said light emitting element emits light having a wavelength in a range from 450nm to 480 nm.

34. (New) The apparatus according to claim 1, wherein said phosphor layer portion comprises Ce:YAG.

35. (New) The apparatus according to claim 1, wherein said phosphor layer portion comprises a uniform thickness.

36. (New) The method according to claim 7, further comprising:

forming a sealant between said light emitting element and said phosphor layer, for sealing said light emitting element, said forming said sealant comprising:

injecting said sealant into said recess; and

fixing said light transmitting portion onto said light emitting element such that said light emitting element is sealed with said sealant.

37. (New) A light emitting apparatus, comprising:

a light emitting element that emits light with a predetermined wavelength;

a molded lens comprising a recessed portion which has a predetermined size and is formed over said light emitting element; and

a phosphor layer formed on a surface of said recessed portion, said phosphor layer including a material which is excited by light emitted from the light emitting element,

wherein a sealant is formed between said light emitting element and said phosphor layer, for sealing said light emitting element.